EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	8	(257/E21.598).ccls. and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/19 09:30
L2	1308	(257/E21.705).ccls. and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/19 09:30
L3	1316	L1 or L2	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/19 09:30
L4	166	L3 and ((glass or silica) near5 (paste or epoxy or solder or resin))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/19 09:31
L5	4	L3 and (((glass or silica) near5 (paste or epoxy or solder or resin)) with (conduct$3)) and (((glass or silica) near5 (paste or epoxy or solder or resin)) with (nonconduct$3 or non-conduct$3 or insulat$3 or dielectric))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/19 09:31
L6	9	L3 and (((glass or silica) with (paste or epoxy or solder or resin)) with (conduct$3)) and (((glass or silica) with (paste or epoxy or solder or resin)) with (nonconduct$3 or non-conduct$3 or insulat$3 or dielectric))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/19 09:32
S138	1254	438/455.ccls. and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:26
S139	298	438/456.ccls. and @ad<"20041029"	US-PGPUB;	OR	ON	2011/10/12

			USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB			12:26
S140	1370	(257/704).ccls. and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:26
S141	1712	(257/E21.211).ccls. and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:26
S142	1476	(257/E23.193).ccls. and @ad<"20041029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:26
S143	2	(S138 or S139 or S140 or S141 or S142) and @pd>"20110526"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:26
S144	24	Knechtel-Roy.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:26
S145	1	S144 and (wafer and (glass adj paste) and conducting and non-conducting).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:26
S146	1	X-Fab.as. and ((glass adj paste) and wafer and conducting and non-conducting).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:27
S147	1	(wafer and (glass adj paste) and conducting and non-conducting).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:28
S148	2	((semiconduct$3 or silicon or Si) near3	US-PGPUB;	OR	ON	2011/10/12

		wafer) and (conduct$3 near5 (glass adj paste)) and ((insulat$3 or dielectric or non-conduct$3) near5 (glass adj paste)) and ((bond$3 or join$3) near5 wafer) and @ad<"20031029"	USPAT; EPO; JPO; DERWENT; IBM_TDB			12:29
S149	2	((semiconduct$3 or silicon or Si) near6 wafer) and (conduct$3 near8 (glass near3 paste)) and ((insulat$3 or dielectric or non-conduct$3) near8 (glass near3 paste)) and ((bond$3 or join$3) near5 wafer) and @ad<"20031029"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:31
S150	6	((semiconduct$3 or silicon or Si) near6 wafer) and (conduct$3 near8 (glass near3 paste)) and ((insulat$3 or dielectric or non-conduct$3) near8 (glass near3 paste)) and ((bond$3 or join$3) with wafer) and @ad<"20031029"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:31
S151	10	((semiconduct$3 or silicon or Si) near6 wafer) and (conduct$3 near8 (glass near3 (paste or solder))) and ((insulat$3 or dielectric or non-conduct$3) near8 (glass near3 (paste or solder))) and ((bond$3 or join$3) with wafer) and @ad<"20031029"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:31
S152	18	((semiconduct$3 or silicon or Si) near6 wafer) and (conduct$3 near8 (glass near3 (paste or solder or resin or adhesive or glue))) and ((insulat$3 or dielectric or non-conduct$3) near8 (glass near3 (paste or solder or resin or adhesive or glue))) and ((bond$3 or join$3) with wafer) and @ad<"20031029"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:44
S155	5709	(S138 or S139 or S140 or S141 or S142)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:47
S157	513	S155 and ((glass or silica) near3 (paste or resin or glue or epoxy or adhesive))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:47
S158	103	S157 and ((bond$3 or join$3) near8 wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:48
S159	26	S158 and ((pre-melt$3 or premelt$3 or melt$3) near9 (paste or glue or resin or adhesive or solder))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO;	OR	ON	2011/10/12 12:48

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
			DERWENT; IBM_TDB			
S161	7	S159 and (conduct$3 near5 (solder or paste or adhesive or resin or glue)) and ((insulat$3 or non-conduct$3 or nonconduct$3 or dielectric) near5 (solder or paste or adhesive or resin or glue))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 12:56
S163	776	(conduct$3 near5 (glass or silica) near5 (solder or paste or adhesive or resin or glue)) and ((insulat$3 or non-conduct$3 or nonconduct$3 or dielectric) near5 (glass or silica) near5 (solder or paste or adhesive or resin or glue)) and @ad<"20031029"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 13:01
S164	3	S163 and ((bond$3 or join$3 or attach$3) near5 wafers!)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/12 13:01

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S165	0	X-Fab.as. and ((glass adj paste) and wafer and conducting and non-conducting).clm.	USPAT; UPAD	OR	ON	2011/10/12 12:27
S166	3	Knechtel-Roy.in.	USPAT; UPAD	OR	ON	2011/10/12 12:28
S167	0	S166 and (wafer and (glass adj paste) and conducting and non-conducting).clm.	USPAT; UPAD	OR	ON	2011/10/12 12:28
S168	0	(wafer and (glass adj paste) and conducting and non-conducting).clm.	USPAT; UPAD	OR	ON	2011/10/12 12:28

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